

## ightarrow ightarrow ightarrow Inductors (Coils) ightarrow Detailed Information

## Inductors (Coils)

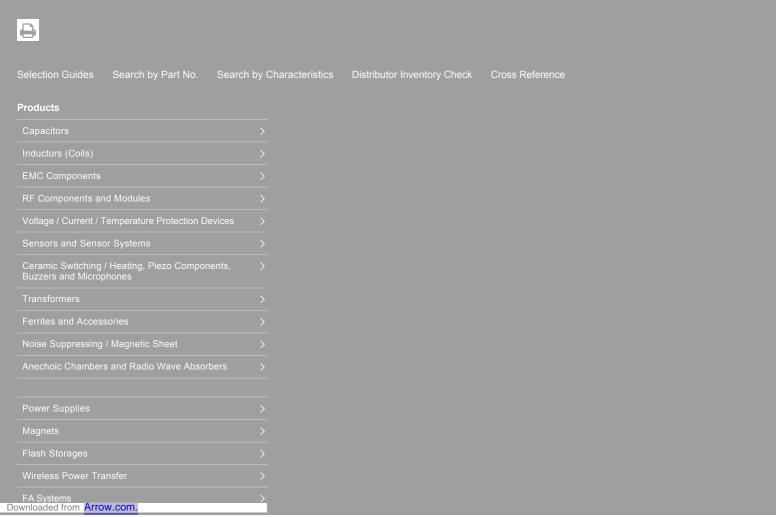
Product Top Pag	ge Search by Part	No. Search by Characte	eristics Cross Refe	erence Catalog	Tech Notes	▼ more
MHQ04	02 <b>P</b> 22NH	T000				Image: State of the system     Image: State of the system
Applications	Commercial Grade					PDF file of this page
Feature	Non-Mag Core Non	Non-Mag Core Non-Magnetic Core (Dielectric Ceramic)			e - new e a	Contact
Series   Type	MHQ-P					Documents
Status	Production (Not Recommended for New Design) Recommended Alternate Part No. : <u>MHQ0402PSA22NHT000</u> (Interc hangeability is not guaranteed.)			and show exe	r reference only mplary products.	Catalog Catalog Control Certificate SVHC/REACH Certificate
Brand	TDK	DK				<ul> <li>Product Lineup</li> <li>[Selection Guide] Inductors for high frequency applications</li> <li>Update</li> </ul>
Size						Sample Kits
Length(L)		0.44r	mm ±0.02mm			Technical Support Tools
Width(W)			0.24mm ±0.02mm			S-parameter
Thickness   Hei	aht		mm ±0.02mm			SPICE Netlist (Simple)
•	Land Pattern (A)		0.15mm to 0.20mm			SPICE Netlist (Precision)
Recommended Land Pattern (B)		0.201	0.20mm Nom.			Equivalent Circuit Model
Recommended Land Pattern (C)		0.18r	0.18mm to 0.20mm			
Electrical Char	racteristics					
Inductance		22nF	22nH ±3% at 500MHz			
Rated Current		140n	140mA			
DC Resistance [Typ.]		1.899	1.89Ω			
DC Resistance [Max.]		3Ω	3Ω			
Self Resonant F	Frequency [Min.]	2GH:	2GHz			
Self Resonant F	Self Resonant Frequency [Typ.]		2.9GHz			
Q [Min.]		10 at	10 at 500MHz			
Q [Typ.]		14 at	t 500MHz			
Other						
	o. Range (Including Se	elf-Temp. Rise) -55 to	o 125°C			
Soldering Method Reflow						
AEC-Q200	5					
Packing				180mm Reel]		
Package Quantity 20000pcs						
Weight		0.000				

**Characteristic Graph** (This is reference data, and does not guarantee the products characteristics.)

Impedance

mpedanc

MHQ0402P22NHT000	MHQ0402P22NHT000		
Change settings	Change settings		
Inductance	Q		
MHQ0402P22NHT000	MHQ0402P22NHT000		
Change settings	Change settings		



Transparent Conductive Film	>	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)		
Solar Cells		
Biosensor		
Application Specific IC (ASIC) Development and Supply		
Application Guides		
Technical Support		
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